



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

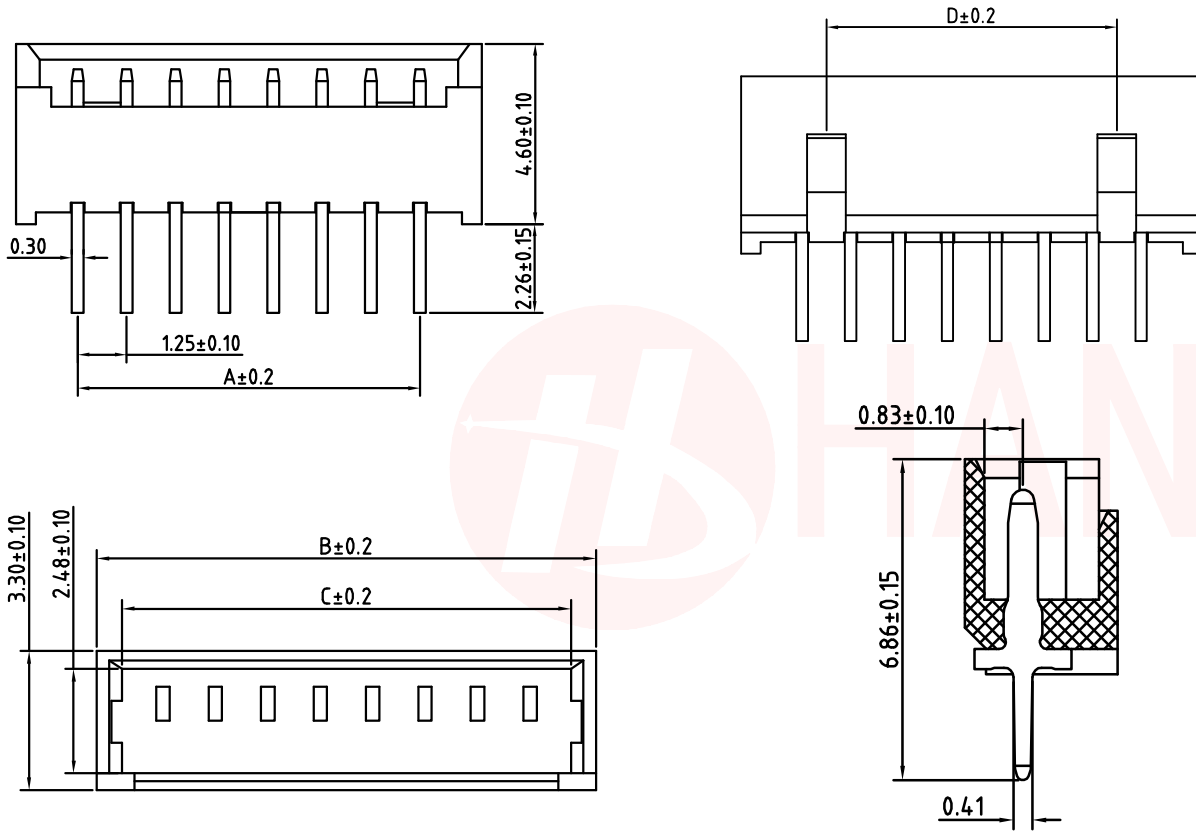
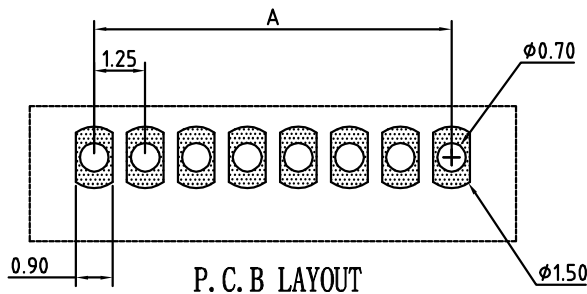


TABLE:

CSG PART NO.	Dimension mm				
	PIN	A	B	C	D
WAFER-MX125Z-2A	2P	1.25	4.40	3.20	
WAFER-MX125Z-3A	3P	2.50	5.65	4.45	
WAFER-MX125Z-4A	4P	3.75	6.90	5.70	2.50
WAFER-MX125Z-5A	5P	5.00	8.15	6.95	3.75
WAFER-MX125Z-6A	6P	6.25	9.40	8.20	5.00
WAFER-MX125Z-7A	7P	7.50	10.65	9.45	6.25
WAFER-MX125Z-8A	8P	8.75	11.90	10.70	7.50
WAFER-MX125Z-9A	9P	10.00	13.15	11.95	8.75
WAFER-MX125Z-10A	10P	11.25	14.40	13.20	10.00
WAFER-MX125Z-11A	11P	12.50	15.65	14.45	11.25
WAFER-MX125Z-12A	12P	13.75	16.90	15.70	12.50
WAFER-MX125Z-13A	13P	15.00	18.15	16.95	13.75
WAFER-MX125Z-14A	14P	16.25	19.40	18.20	15.00
WAFER-MX125Z-15A	15P	17.50	20.65	19.45	16.25
WAFER-MX125Z-16A	16P	18.75	21.90	20.70	17.50

技术要求:

- 1、塑件材料: PA66 (UL-94V-0)
- 2、接触件: 黄铜镀锡
- 3、接触电阻:  $\leq 10\text{m}\Omega$
- 4、绝缘电阻:  $\geq 1000\text{M}\Omega$
- 5、额定电压: 125V AC DC
- 6、额定电流: 1.0A AC DC
- 7、耐压: 能承受1000V AC/Minute
- 8、工作温度:  $-25^{\circ} \sim +85^{\circ}$
- 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $235_{-5}^{+5}$ , 时间 $2.5 \pm 0.5$ 秒
- 10、铅和镉等六大有害物质含量要符合环保要求



序号	名称	材料	电镀 (锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
1	端子/Contact	黄铜	
2	基座/Wafer	PA66 (UL94V-0)	本色
UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS: ANGLES:		TITLE: WAFER MX 1.25MM 直针 DIP TYPE	
X :±0.20	X :±2°	DWN	xiong PART NO. WAFER-MX125Z-NA
X.X :±0.10	X.X :±1°	CHKD	lee SCALE:1:1 UNIT: mm
X.XX :±0.05		APVD	wang SIZE: A4 SHEET:10F 1 REV: A4
CUSTOMER COPY			